



## **TABLE OF CONTENTS**

1.0 SCOPE

**2.0 APPLICABLE DOCUMENTS** 

**3.0 MATERIAL SPECIFICATIONS** 

**3.1 DESIGN AND CONSTRUCTION** 

**3.2 MATERIALS** 

4.0 RATINGS

5.0 PERFORMANCE AND TEST DESCRIPTION

6.0 INFRARED RELOLW CONDITIONS

7.0 MOISTURE RESISTANCE CONDITIONS

**8.0 APPLICATION NOTES** 

	REV	Α	А	Α	А	А	А	А	Α															
	SHT	1	2	3	4	5	6	7	8															
	REVISE ON PC ONLY				TIT	ĽΕ	~~ ~				. ~ .	_	~ ~					~	_					
A <b>PDR MXT-TM0008</b>						SD/IO H	O MH EAD	EMC ER	)RY WI	FH I	EJE	СТ	NN OR REF	ME	CHA	FOR NISM	CAR [ &	D						
	DEV	DECONDENCI					THI	S DOC											TO MOI	EX IN	C.			
	KEV	REV DESCRIPTION				AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																		
	DESI	GN (	CON	TROI	_	S	TAT	US	WRITTEN BY: CHECKED BY: APPROVED BY: DATE: YR / MO /					) / DA'	Y									
		MZ	ХT				Μ		M	AX CH	HANG	W	ILSO	Ν		ERI	CK			20	003/08/0	5		
DC	CUMENT	NO.							İ										F	ILE N	IAME	SH	T NC	).
	PS-67913-002					Ś	<sup>7</sup> CR	ITICAL	= 0	▼	MAJ	OR	=0			PS	-6791 .PD	13-002 DF	1 0	F 8				
	ES-40000-3996 REV. A					V. A	SH	EET :	3 95/N	IAR/1	) E	EC U	5-092	26	DCE	RD0	3.SA	М						





## **1.0 SCOPE**

This specification covers the SD MEMORY CONNECTOR series.

### 2.0 APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herewith. In the event of conflict between the requirements of the specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of the specification and the referenced documents, this specification shall take precedence.

MIL-STD-202Test Methods for Electronic and Electrical Component PartsMIL-STD-1344Test Methods for Electrical Connectors

### **3.0 MATERIAL SPECIFICATIONS**

#### 3.1 Design and Construction

Connector shall be of the design, construction and physical dimensions specified on the applicable sales drawing

3.2 Materials Refer to respective sales and Engineering drawings

#### 4.0 RATINGS

**4.1 Voltage** 100 Volts DC per contact for Header 3.6 Volts DC per contact for Card

#### 4.2 Current

0.5 Amps per contact

#### **5.0 Performance and Test Description**

Connector shall be designed to meet the electrical, mechanical and environmental performance requirements specified in 5.0

GENERAL REQUIREMENTS

Operating Temperature Range: -25 °C to +90 °C Storage Temperature Range: -40 °C to +90 °C

		REVISE ON PC ONLY	TITLE		CADD			
	А	SEE SHEET 1	HEADER WITH EJEC	SD MEMORY CARD CONNECTOR FOR CARD HEADER WITH EJECTOR MECHANISM				
REV     DESCRIPTION     THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSI					0 mollin			
DOC	CUMENT 1	NO.	DIMENSION CLASS:	FILE NAME	SHEET			
PS-67913-002			$\mathbf{\nabla}$ RITICAL = 0 $\mathbf{\nabla}$ MAJOR = 0	PS-67913-002. PDF	2			
	PDF							





# **ELECTRICAL**

Item	Test Condition	Requirement
Contact Resistance	Mated dummy card dry circuit measurement, 20mV Max. 10mA Max.	<b>100</b> milliohm Maximum initial & After test Including: Connector contacts Detection switch
Insulation Resistance	Apply 500V DC between adjacent termi- nals or ground (base upon MIL-STD-202 method 302)	<ul><li>1000 Megohms Minimum initial</li><li>100 Megohms Minimum After test</li></ul>
Withstanding Voltage	Apply 500 V AC for 1 min. between adjacent terminals or ground (base upon MIL-STD-202 method 301)	No breakdown

		REVISE ON PC ONLY	TITLE		GADD			
	А	SEE SHEET 1	SD MEMORY CARD CON HEADER WITH EJEC	SD MEMORY CARD CONNECTOR FOR CARD HEADER WITH EJECTOR MECHANISM				
	REV	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
DOCUMENT NO.			DIMENSION CLASS:	FILE NAME	SHEET			
PS-67913-002			$\bigcirc$ RITICAL = 0 $\bigcirc$ MAJOR = 0	PS-67913-002. PDF	3			
	.PDF							





# **MECHANICAL**

Item	Test Condition	Requirement
Push in strength	The card is inserted in positive and the opposite direction and the load of 19.6 (2 kgf) is added with 1 minute and repeated 5 times.	Appearance : No Damage
Card Insertion force	Push the card at the speed rate of 25 +/-3mm/minute on card pushing position.	Insertion force:15N Max ( 1.5 kgf Max.)
Card Retention Force	Pull out the card directly at the speed rate of 25 +/-3mm/minute on card lock position.	Withdrawal force: 4 N Min. ( 0.4kgf Min.)
Terminal Normal Force	Apply axial push-out force at the speed of 25 +/-3 mm/min.	0.2 N Min. Per Pin (0.02 kgf Min. per pin)
Durability (Push in/ push out)	Insertion and extraction are repeated 10,000 cycles with the actually card at the speed rate of 400-600 cycles/hour. Exchange the actually card every 2000 cycles.	Appearance :No damage Contact Resistance: 100 milliohm Max. measuring by dummy card

	R	EVISE ON PC ONLY	TITLE SD MEMORY CARD CONNECTOR FOR CARD HEADER WITH EJECTOR MECHANISM				
	А	SEE SHEET 1					
-	REV	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION TH. INC. AND SHOULD NOT BE USED WITHOUT				
DOCU	UMENT N	0.	DIMENSION CLASS:	FILE NAME	SHEET		
PS-67913-002			$\mathbf{\nabla} \mathbf{RITICAL} = 0 \mathbf{\nabla} \mathbf{MAJOR} = 0$	PS-67913-002. PDF	4		
	.PDF						





# **ENVIRONMENTAL**

	It	em	Test	t Condition	Re	equirement	
	following vibration of 2 hours in each of axis, passing DC 1 Amplitude : Frequency shall be traversed i (MIL-STD-202 MetShockMate dummy card following shock co be applied along 3 axis, passing DC 1 test. (Total of 18 sl Test Pulse: Half S Peak Value : 490m Duration : 11ms (MIL-STD-202 MetMoisture ResistanceMatedummy card a tions specified on p test specimens sha during only 5 out of consisting of only s performed, after wf shall be conditioned tions for 24 hours.			MAX.	No damage. ance: 100 milliohm 1 microsecond M/		
			following shock of be applied along 3 axis, passing DC test. (Total of 18 s Test Pulse: Half Peak Value : 490r Duration : 11ms	Sine. n/s²	Appearance : No damage.     Contact resistance: 100 milliohms     MAX.     Discontinuity: 1 microsecond MAX.     Appearance : No damage     Contact resistance: 100 milliohms     MAX.     Discontinuity: 1 microsecond MAX.     Appearance : No damage     Contact resistance: 100 milliohms     MAX.     Dielectric strength : Must meet     electrical requirement.     Insulation resistance : 100 Megohms     Minimum.		
			tions specified on test specimens sh during only 5 out of consisting of only performed, after w shall be conditioned				
	Solde	erability	Dip solder tails int	o the molten solder ( held ) up to 0.5mm from the tip	Solder coverage : 95% Min.		
	Tempera	ature Rise		y card measure the It the rated current after	Temperature i 30°C Maximu		
	REVISE ON PC ONLY			TITLE SD MEMORY		INECTOD FOD	CADD
	A SEE SHEET 1		SD MEMORY HEADER V THIS DOCUMENT CONTAINS IN		NECTOR FOR FOR MECHAN AT IS PROPRIETARY T		
	REV		CRIPTION	INC. AND SHOULD NOT	BE USED WITHOU	JT WRITTEN PERMISSI	ON
DOC	DOCUMENT NO. <b>PS-67913-002</b>		DIMENSION CLASS: $\overrightarrow{C}$ RITICAL = 0 MAJOR = 0 PDF		SHEET 5		





ENGLISH	

	Item	,	Test Condition		Requirement		
Tempe	conditions for of the exposur shall be condi conditions for specified mea performed. 1 cycle a) -55 b) +8 Trainsit tie shal		Appearance : No damage 5 cycles. Upon completions e period, the test specimens ions at ambient room 1 to 2 hours, after which the surements shall be $+5^{\circ}/-5^{\circ}C$ 30min. $5 +2^{\circ}/-2^{\circ}C$ 30min. be within 3 min.			hm	
Heat	Resistance	/-2°C for 96 hou exposure perio be conditions a for 1 to 2 hours	r and exposed to $85 ^{\circ}C + 2^{\circ}$ urs. Upon completions of the d, the test specimens shall t ambient room conditions s, after which the specified shall be performed Method 108)	Appearance : No damage. Contact resistance : 100 milliohm MAX.			
Cold	+2°/ the sha con spe		r and exposed to -40°C hours. Upon completion of eriod, the test specimens ons at ambient room to 2 hours, after which the urements shall be -STD-202 Method 108)	Appearance : No damage. Contact resistance : 100 milliohm MAX.			
S	alt spray	following salt m completion of th deposites shall wash or dip in n the specified m performed NaCL solution concentration : Spray time : 48	hours erature : 35 +2°C/-2 °C.	Appearance : No damage. Contact resistance : 100 milliohm MAX.			
SO <sub>2</sub> Gas Mate dum SO <sub>2</sub> gas, a		$SO_2$ gas, anbient	· · ·		Appearance : No damage. Contact resistance : 100 milliohm MAX.		
	DEVICE ON DO						
REVISE ON PC ONLY   A SEE SHEET 1   REV DESCRIPTION		TITLE <b>SD MEMORY CARD CONNECTOR FOR CARD</b> <b>HEADER WITH EJECTOR MECHANISM</b> THIS DOCUMENT CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX					
REV CUMENT N			INC. AND SHOULD NOT BE DIMENSION CLASS:	USED WITHOU	JT WRITTEN PERMISS	ION SHEET	
PS-67913-002			$\mathbf{C}$ RITICAL = 0 $\mathbf{V}$ MAJOH	PS-67913-002			





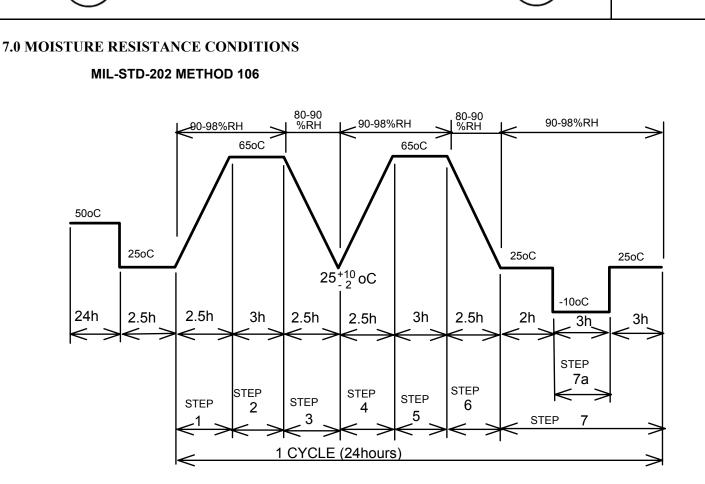
# 6.0 INFRARED RELOLW CONDITIONS

	Item		Test Condition	R	equirement	
	Resistance to soldering Heat	3 deg C/sec Max 60~120 sec (Pre-heat 150-1 (NOTE) 1. Please check the reflow so 2. Thickness of the cream so After reflow process.	TEMPERATURE CONDITION GRAPH TEMPERATURE ON BOARD PATTERN SIDE TWICE 200 deg C min. cooling in still 230 deg C Min	Appearance	e: No Dama After 2 times reflow	ige . of
	REVISE ON	PC ONLY	TITLE			
		EE SHEET 1	SD MEMORY CARI HEADER WITH	D CONNE	CTOR FOR MECHAN	CARD ISM
		SCRIPTION	THIS DOCUMENT CONTAINS INFORMA INC. AND SHOULD NOT BE USED			
DOC	CUMENT NO.		DIMENSION CLASS:		LE NAME	SHEET
	PS-67913	-002	$\bigtriangledown$ RITICAL = 0MAJOR = 0PS-67913-002. PDF7			7
			.PDF			





LANGUAGE



# **8.0 APPLICATION NOTES**

# 8.1 washing after soldering

Please wash only the soldering part partially when washing after this item is soldered when a whole soaking etc. are. washed, the insertion and extraction of the card might become difficult.

		REVISE ON PC ONLY	TITLE					
	А	SEE SHEET 1	SD MEMORY CARD CON	SD MEMORY CARD CONNECTOR FOR CARD HEADER WITH EJECTOR MECHANISM				
	REV	DESCRIPTION	THIS DOCUMENT CONTAINS INFORMATION TH INC. AND SHOULD NOT BE USED WITHO					
DOC	CUMENT N	NO.	DIMENSION CLASS:	FILE NAME	SHEET			
PS-67913-002			$\mathbf{\nabla} \mathbf{RITICAL} = 0 \mathbf{\nabla} \mathbf{MAJOR} = 0$	PS-67913-002. PDF	8			
	PDF							